L	Hits	Search Text		
Number	<b>:</b>		DB	m:
1	11213	die (adj4 pad		Time stamp
	1	, ,	USPAT;	2002 (
	į		US-PGPUB;	2003/02/22
			EPO; JPO;	11:22
2	4710701	heat (her5) (sink spreader slug metal	DERWENT;	1
2	4/10/91	radiato(f5) (sink spreader al.	IBM TDB	1
		radiate) \ reduct sing metal	USPAT;	2002 10-
			US-PGPUB;	2003/02/22
			EPO; JPO;	11:25
3	5189	wire and (di)	DERWENT;	
,	3103	wire and (di adja pad) and "4"	IBM TDB	1
		and 4	USPAT;	2002 (25)
			US-PGPUB;	2003/02/22
		1	EPO; JPO;	11:25
1	6167	(semi-conductor chandice ic (integrated	US-PGF	1
1	0703	(semiconductor chip dice ic (integrated adj circuit) die) and (die adj4 pad) and (wire wiring)	EPO; JPO;	
		(wire wiring)	DERWENT;	
		("I'm willing)	IBM TDB	100/00
		/ . /:=+ograted	USPAT;	2003/02/22
5	6484	(semiconductor chip dic ic (integrated and later respect die) and (die adj4 pad) and	US-PGPUB;	11:27
	0.101	iani cilcuiti uiti air	EPO; JPO;	
\		(wire wiring wireh,nd)	DERWENT;	
		("	IBM TDB	100 (00
		, integrated	USPAT;	2003/02/22
6	2698	((semiconductor chip dice ic (integrated	US-PGPUB;	11:29
•		((semiconductor chip dice it (integral) and adj circuit) die) and (die adj4 pad) and adj circuit) wirehend) and (bga ball	EPO; JPO;	
	*		DERWENT;	
	V	bump flipchip (flip adj chip))	IBM_TDB	
i		sign is (integrated	USPAT;	2003/02/22
.7	2137	(((semiconductor chip dice ic (incop) adj circuit) die) and (die adj4 pad) and adj circuit) and (bga ball	US-PGPUB;	11:29
		adj circuit) die) and (die adj. Fall	EPO; JPO;	1
		adj circuit) die) and (ure wiring wirebond)) and (bga ball (wire wiring wirebond)) and (bga ball (blip))) and	DERWENT;	
		bump flipchip (III) adj chizpiii	IBM_TDB	2003/02/22
		N euhstrate	USPAT;	1
8	1848	1) and correct ton 1 and	US-PGPUB;	11:30
		(semiconductor chip die) and (die	EPO; JPO;	
1		(ill egrated adj circuit, die, wirebond)) and	DERWENT;	1
		adj4 ad) and (wire willing wild adj chip))   (bga bal bump flipchip (flip adj chip))	IBM_TDB	1
i		(bga bal bump IIIponip (IIIp		2003/02/22
1		and substrate)	USPAT;	1 1
9	1390	(((semicondactor chip dice ic	US-PGPUB;	
		lintograted abi circuit) dle) and (uic	EPO; JPO;	
			d DERWENT;	1
1		(bga ball bump flighting (flip adj chip))	) IBM_TDB	1
	ł	and substrate)) and (epoxy encapsulant		1
		encapsulation)		2003/02/22
1		s l ( ( === lid cover top ) and . \	USPAT;	1
10	35	1	US-PGPUB	; 11:32
		i i i i i i i i i i i i i i i i i i i	EPO; JPO	;
-   -		I II III III WILEDONGII A	nd DERWENT;	
	-	in the line of the	)) IBM_TDB	1
	ł	The state of the s	1	
		encapsulation)) and (retainer ring guar	d)	
1	i	encapsulation, and (235		•

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